

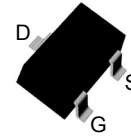
## Features

- 60V/3A  
 $R_{DS(ON)} = 74\text{m}\Omega(\text{typ.}) @ V_{GS} = 10\text{V}$   
 $R_{DS(ON)} = 84\text{m}\Omega(\text{typ.}) @ V_{GS} = 4.5\text{V}$
- 100% UIS +  $R_g$  Tested
- Reliable and Rugged
- Lead Free and Green Devices Available  
(RoHS Compliant)

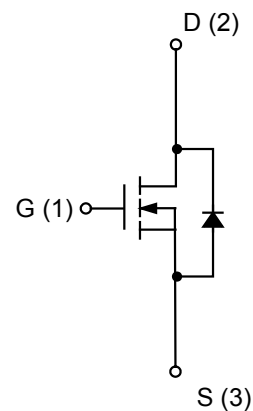
## Applications

- Power Management in DC/AC Inverter Systems.

## Pin Description



Top View of SOT-23-3



N-Channel MOSFET

**Absolute Maximum Ratings** ( $T_A=25^{\circ}\text{C}$  Unless Otherwise Noted)

| Symbol                        | Parameter                              |                      | Rating     | Unit |
|-------------------------------|----------------------------------------|----------------------|------------|------|
| Common Ratings                |                                        |                      |            |      |
| V <sub>DSS</sub>              | Drain-Source Voltage                   |                      | 60         | V    |
| V <sub>GSS</sub>              | Gate-Source Voltage                    |                      | ±12        |      |
| T <sub>J</sub>                | Maximum Junction Temperature           |                      | 150        | °C   |
| T <sub>STG</sub>              | Storage Temperature Range              |                      | -55 to 150 |      |
| I <sub>S</sub>                | Diode Continuous Forward Current       | T <sub>A</sub> =25°C | 3          | A    |
| I <sub>D</sub>                | Continuous Drain Current               | T <sub>A</sub> =25°C | 3          | A    |
|                               |                                        | T <sub>A</sub> =70°C | 2.3        |      |
| I <sub>DM</sub> <sup>a</sup>  | Pulsed Drain Current                   | T <sub>A</sub> =25°C | 9          | A    |
| P <sub>D</sub>                | Maximum Power Dissipation              | T <sub>A</sub> =25°C | 1          | W    |
|                               |                                        | T <sub>A</sub> =70°C | 0.64       |      |
| R <sub>θJA</sub> <sup>c</sup> | Thermal Resistance-Junction to Ambient | Steady State         | 125        | °C/W |
| I <sub>AS</sub> <sup>b</sup>  | Avalanche Current, Single pulse        | L=0.5mH              | 5          | A    |
| E <sub>AS</sub> <sup>b</sup>  | Avalanche Energy, Single pulse         | L=0.5mH              | 6          | mJ   |

Note a : Pulse width limited by max junction temperature.

Note b : UIS tested and pulse width limited by maximum junction temperature  $150^{\circ}\text{C}$  (initial temperature  $T_J=25^{\circ}\text{C}$ ).

Note c : Surface Mounted on  $1\text{in}^2$  pad area.

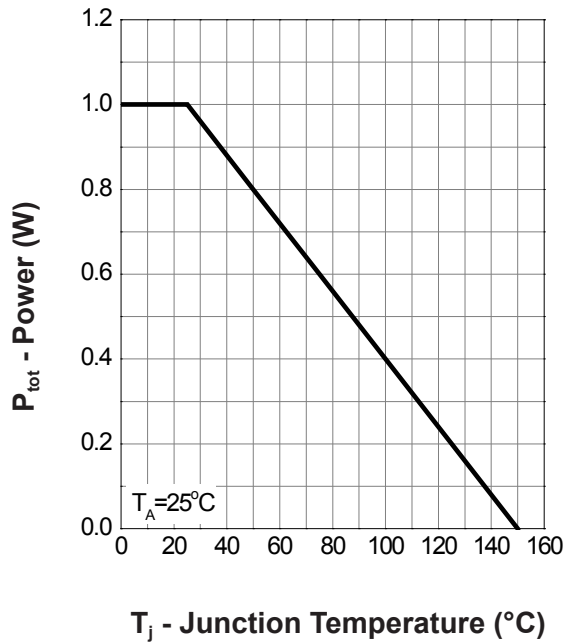
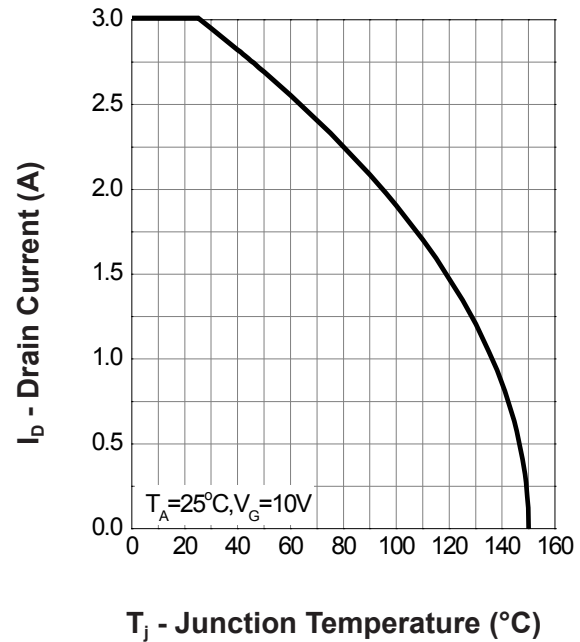
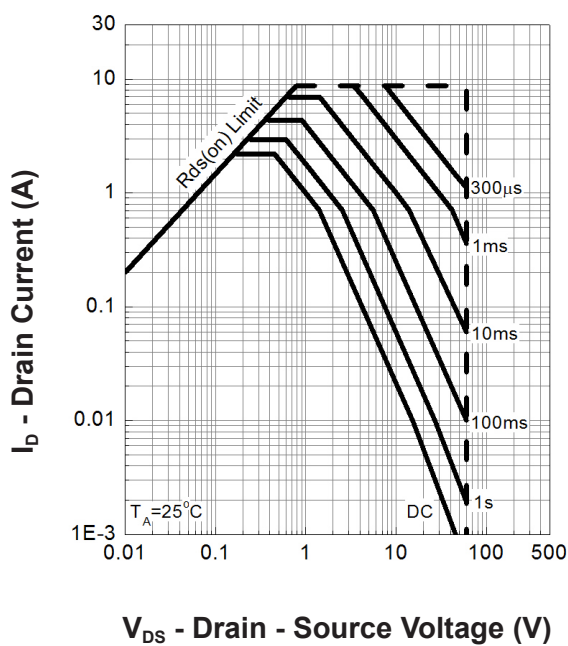
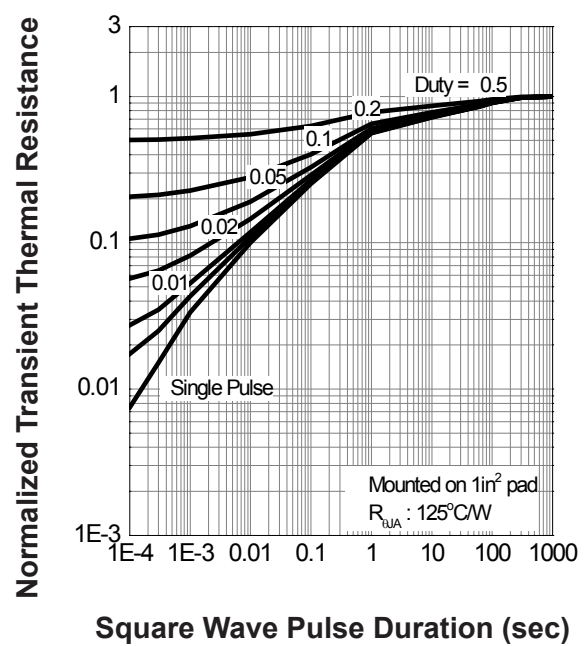
**Electrical Characteristics** ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

| Symbol                                   | Parameter                        | Test Conditions                                                                                                 | Min. | Typ. | Max. | Unit |
|------------------------------------------|----------------------------------|-----------------------------------------------------------------------------------------------------------------|------|------|------|------|
| Static Characteristics                   |                                  |                                                                                                                 |      |      |      |      |
| BV <sub>DSS</sub>                        | Drain-Source Breakdown Voltage   | V <sub>GS</sub> =0V, I <sub>DS</sub> =250μA                                                                     | 60   | -    | -    | V    |
| I <sub>DSS</sub>                         | Zero Gate Voltage Drain Current  | V <sub>DS</sub> =48V, V <sub>GS</sub> =0V                                                                       | -    | -    | 1    | μA   |
|                                          |                                  | T <sub>J</sub> =85°C                                                                                            | -    | -    | 30   |      |
| V <sub>GS(th)</sub>                      | Gate Threshold Voltage           | V <sub>DS</sub> =V <sub>GS</sub> , I <sub>DS</sub> =250μA                                                       | 0.7  | 1.0  | 1.3  | V    |
| I <sub>GSS</sub>                         | Gate Leakage Current             | V <sub>GS</sub> =±12V , V <sub>DS</sub> =0V                                                                     | -    | -    | ±100 | nA   |
| R <sub>DS(ON)</sub> <sup>d</sup>         | Drain-Source On-state Resistance | V <sub>GS</sub> =10V, I <sub>DS</sub> =2A                                                                       | -    | 74   | 100  | mΩ   |
|                                          |                                  | V <sub>GS</sub> =4.5V, I <sub>DS</sub> =2A                                                                      | -    | 84   | 120  | mΩ   |
| Diode Characteristics                    |                                  |                                                                                                                 |      |      |      |      |
| V <sub>SD</sub> <sup>d</sup>             | Diode Forward Voltage            | I <sub>SD</sub> =1A , V <sub>GS</sub> =0V                                                                       | -    | 0.8  | 1.1  | V    |
| t <sub>rr</sub>                          | Reverse Recovery Time            | I <sub>SD</sub> =1A, dI <sub>SD</sub> /dt=100A/ms                                                               | -    | 14   | -    | ns   |
| Q <sub>rr</sub>                          | Reverse Recovery Charge          |                                                                                                                 | -    | 11   | -    | nC   |
| Dynamic Characteristics <sup>e</sup>     |                                  |                                                                                                                 |      |      |      |      |
| R <sub>G</sub>                           | Gate Resistance                  | V <sub>GS</sub> =0V,V <sub>DS</sub> =0V,f=1MHz                                                                  | -    | 2.5  | -    | Ω    |
| C <sub>iss</sub>                         | Input Capacitance                | V <sub>GS</sub> =0V,<br>V <sub>DS</sub> =30V,<br>Frequency=1.0MHz                                               | -    | 270  | 350  | pF   |
| C <sub>oss</sub>                         | Output Capacitance               |                                                                                                                 | -    | 30   | -    |      |
| C <sub>rss</sub>                         | Reverse Transfer Capacitance     |                                                                                                                 | -    | 15   | -    |      |
| t <sub>d(ON)</sub>                       | Turn-on Delay Time               | V <sub>DD</sub> =30V, R <sub>L</sub> =30Ω,<br>I <sub>DS</sub> =1A, V <sub>GEN</sub> =10V,<br>R <sub>G</sub> =6Ω | -    | 5    | 9    | ns   |
| t <sub>r</sub>                           | Turn-on Rise Time                |                                                                                                                 | -    | 8    | 15   |      |
| t <sub>d(OFF)</sub>                      | Turn-off Delay Time              |                                                                                                                 | -    | 14   | 25   |      |
| t <sub>f</sub>                           | Turn-off Fall Time               |                                                                                                                 | -    | 3    | 6    |      |
| Gate Charge Characteristics <sup>e</sup> |                                  |                                                                                                                 |      |      |      |      |
| Q <sub>g</sub>                           | Total Gate Charge                | V <sub>DS</sub> =30V, V <sub>GS</sub> =4.5V,<br>I <sub>DS</sub> =2A                                             | -    | 3.5  | -    | nC   |
| Q <sub>g</sub>                           | Total Gate Charge                | V <sub>DS</sub> =30V, V <sub>GS</sub> =10V,<br>I <sub>DS</sub> =2A                                              | -    | 7    | 10   |      |
| Q <sub>gs</sub>                          | Gate-Source Charge               |                                                                                                                 | -    | 0.8  | -    |      |
| Q <sub>gd</sub>                          | Gate-Drain Charge                |                                                                                                                 | -    | 1.2  | -    |      |

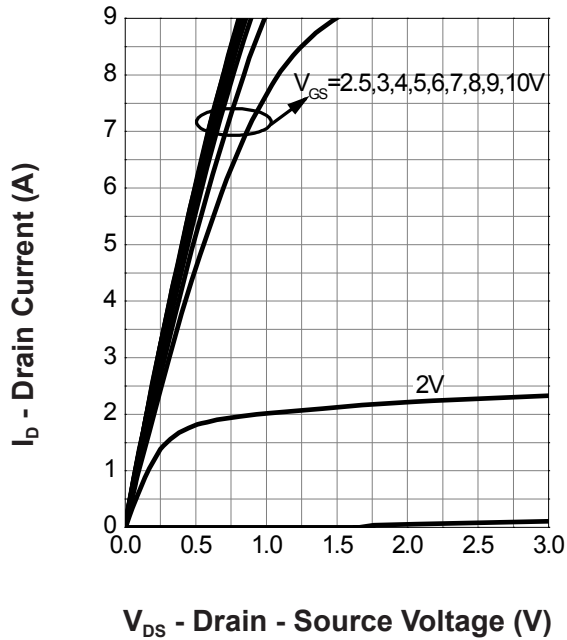
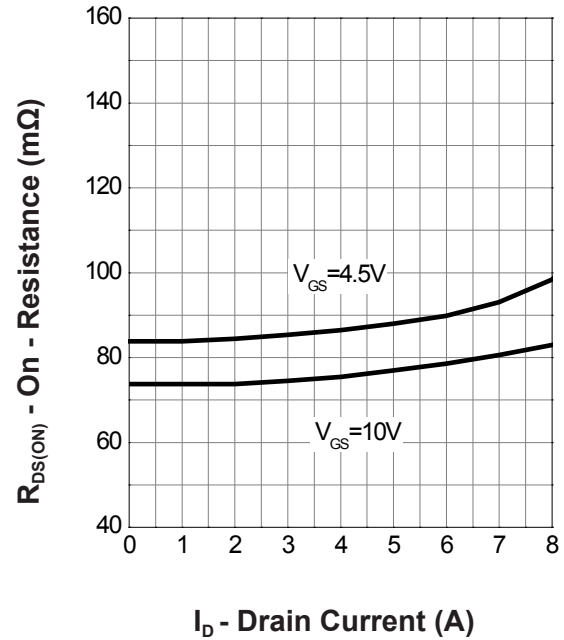
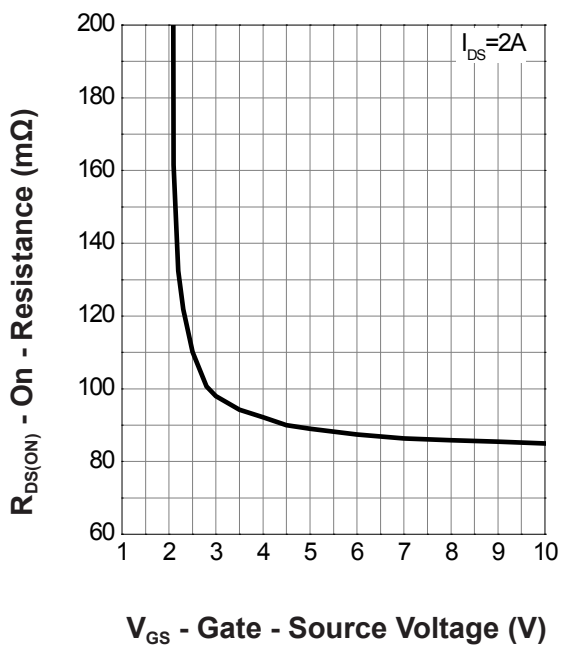
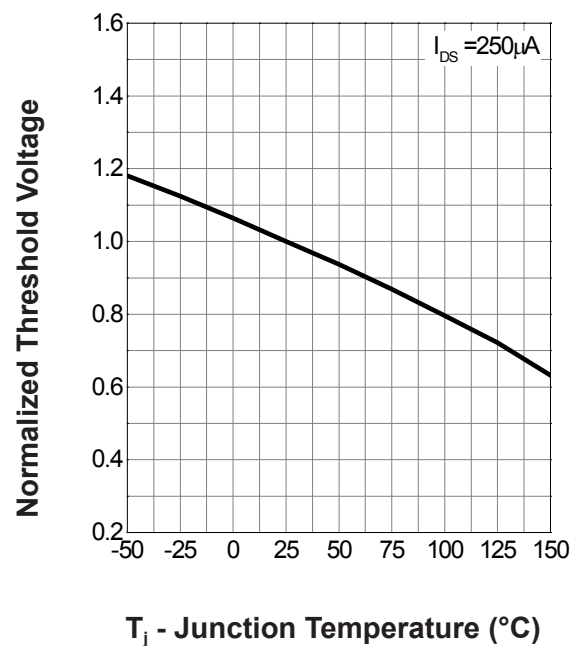
Note d : Pulse test ; pulse width $\leq 300ms$ , duty cycle $\leq 2\%$ .

Note e : Guaranteed by design, not subject to production testing.

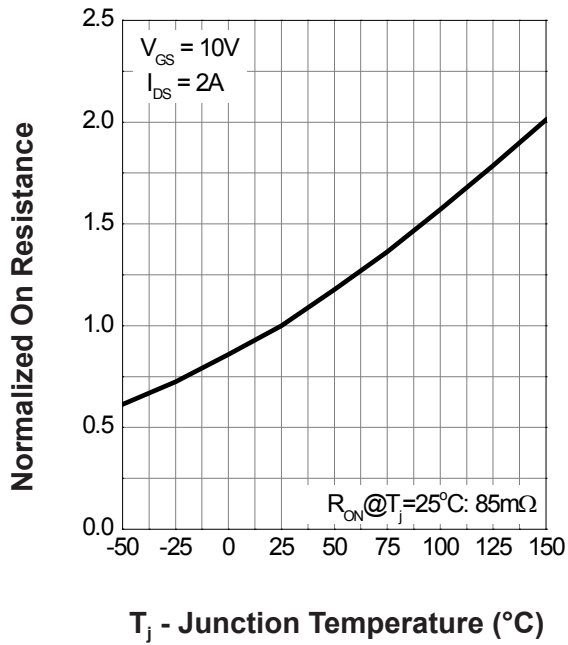
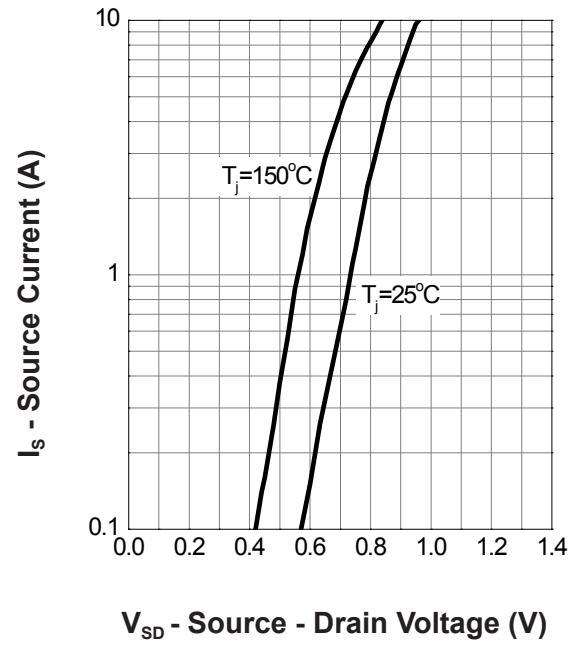
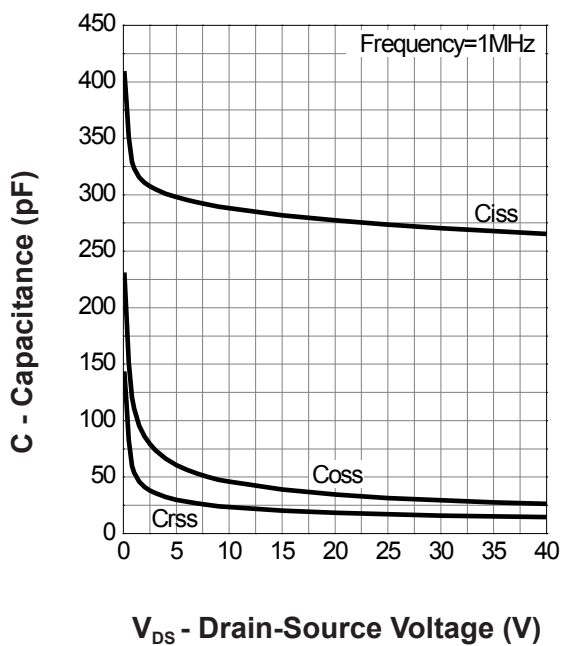
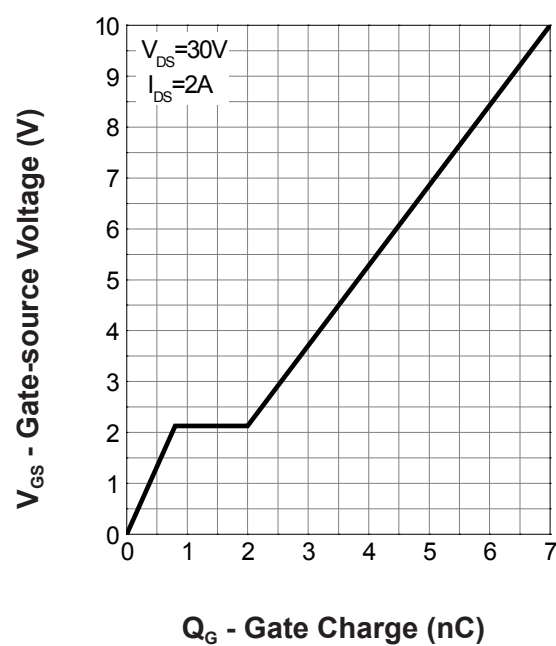
## Typical Operating Characteristics

**Power Dissipation**

**Drain Current**

**Safe Operation Area**

**Thermal Transient Impedance**


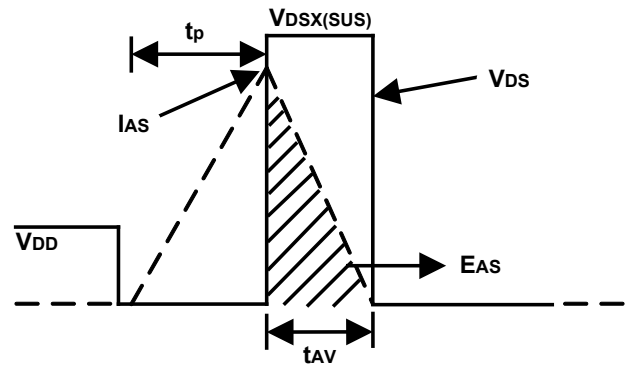
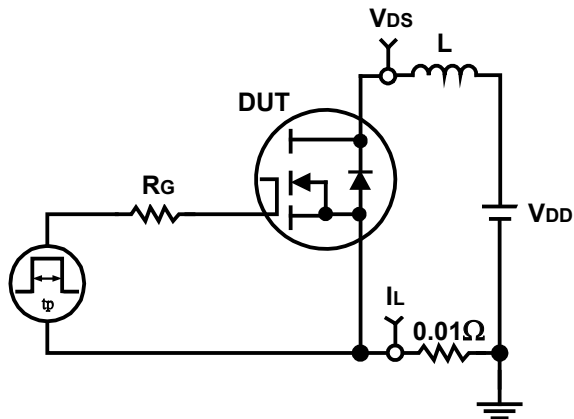
## Typical Operating Characteristics(Cont.)

**Output Characteristics**

**Drain-Source On Resistance**

**Gate-Source On Resistance**

**Gate Threshold Voltage**


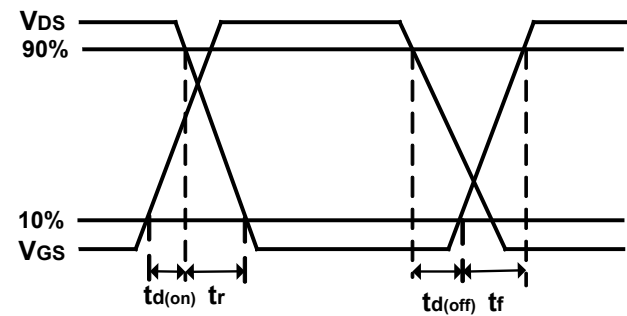
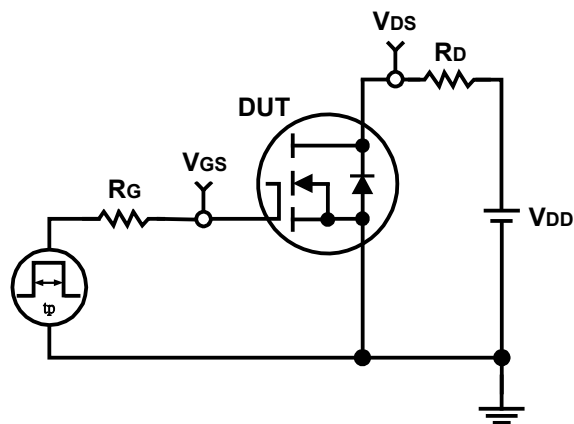
## Typical Operating Characteristics(Cont.)

**Drain-Source On Resistance**

**Source-Drain Diode Forward**

**Capacitance**

**Gate Charge**


## Avalanche Test Circuit and Waveforms

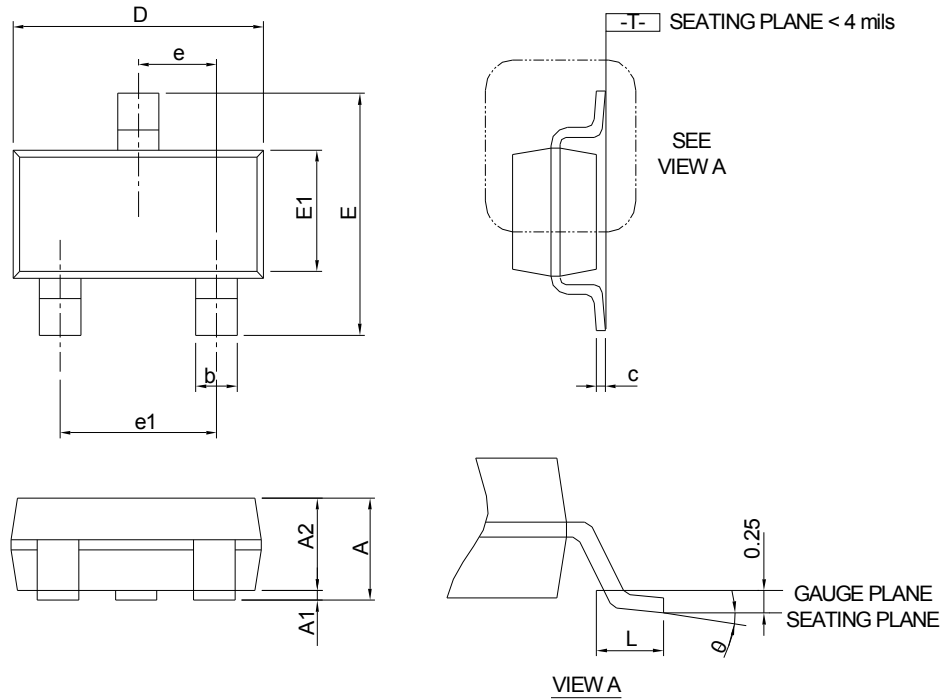


## Switching Time Test Circuit and Waveforms



## Package Information

### SOT-23-3



| SYMBOL | SOT-23-3    |      |           |       |
|--------|-------------|------|-----------|-------|
|        | MILLIMETERS |      | INCHES    |       |
|        | MIN.        | MAX. | MIN.      | MAX.  |
| A      |             | 1.20 |           | 0.047 |
| A1     | 0.00        | 0.08 | 0.000     | 0.003 |
| A2     | 0.90        | 1.12 | 0.035     | 0.044 |
| b      | 0.30        | 0.50 | 0.012     | 0.020 |
| c      | 0.08        | 0.22 | 0.003     | 0.009 |
| D      | 2.70        | 3.10 | 0.106     | 0.122 |
| E      | 2.60        | 3.00 | 0.102     | 0.118 |
| E1     | 1.40        | 1.80 | 0.055     | 0.071 |
| e      | 0.95 BSC    |      | 0.037 BSC |       |
| e1     | 1.90 BSC    |      | 0.075 BSC |       |
| L      | 0.30        | 0.60 | 0.012     | 0.024 |
| θ      | 0°          | 8°   | 0°        | 8°    |

Note : Dimension D and E1 do not include mold flash, protrusions or gate burrs. Mold flash, protrusion or gate burrs shall not exceed 10 mil per side.

### RECOMMENDED LAND PATTERN

